



**Computing Platform Service Partner**

# **FES-6110**

## **Environment Test Report**

**Report NO: 10I020006**

Issued by: **Rex-Chang** / **04/01/2010**  
\_\_\_\_\_  
Test Engineer Date

Reviewed by: **Jansin Lee** / **04/01/2010**  
\_\_\_\_\_  
Sr. Manager Date

# Test item list

1. <i>Test item list</i> -----	2
2. <i>Configuration of EUT</i> -----	3
3. <i>Temperature rise test</i> -----	4
4. <i>Temperature cycle operation test</i> -----	8
5. <i>High temperature storage test</i> -----	9
6. <i>Low temperature storage test</i> -----	10
7. <i>Humidity test</i> -----	11
8. <i>Cold start and hot start test</i> -----	12

## Testing Result

Num	Test item list	Result	Remark
1	Temperature rise test	Pass	
2	Temperature cycle operation test	Pass	
3	High temperature storage test	Pass	
4	Low temperature storage test	Pass	
5	Temperature variation operation test	Pass	
6	Cold start and hot start test	Pass	

# Configuration of EUT

Num	Item	Spec
1.	Mounting Chassis:	FES-6110
	1. PCB / CPU	IMBE-945G A1.0 (BIOS: 1.0) / Intel Atom N270 / 1.6GHz
	3. Memory	Transcend DDR2-667 1GB / ELPIDA E5108AJBG
	4. 2.5" SATA SSD	Transcend ST23SGDS52-S / 32GB
	5. Test Software	Windows XP / Run PassMark Burn In Test 4.0 Pro
2.	Mini Card	AzureWave AW-VD904
3.	Adapter	FSP FSP060-DBAB1

## Heat Sink



**Test Date:** 03-19-2010

**Test Product:** FES-6110

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference EN 61131-2(94), UL508 (94)

**Temperature Measurement:**

40 Channel Thermal Recorder:

YOKOGAWA Inc,

Model: DA100-13-1D

Date of Calibration: 12/08/09

Serial Number: 12A323190

**Test Condition:**

Ambient temperature: 45dC

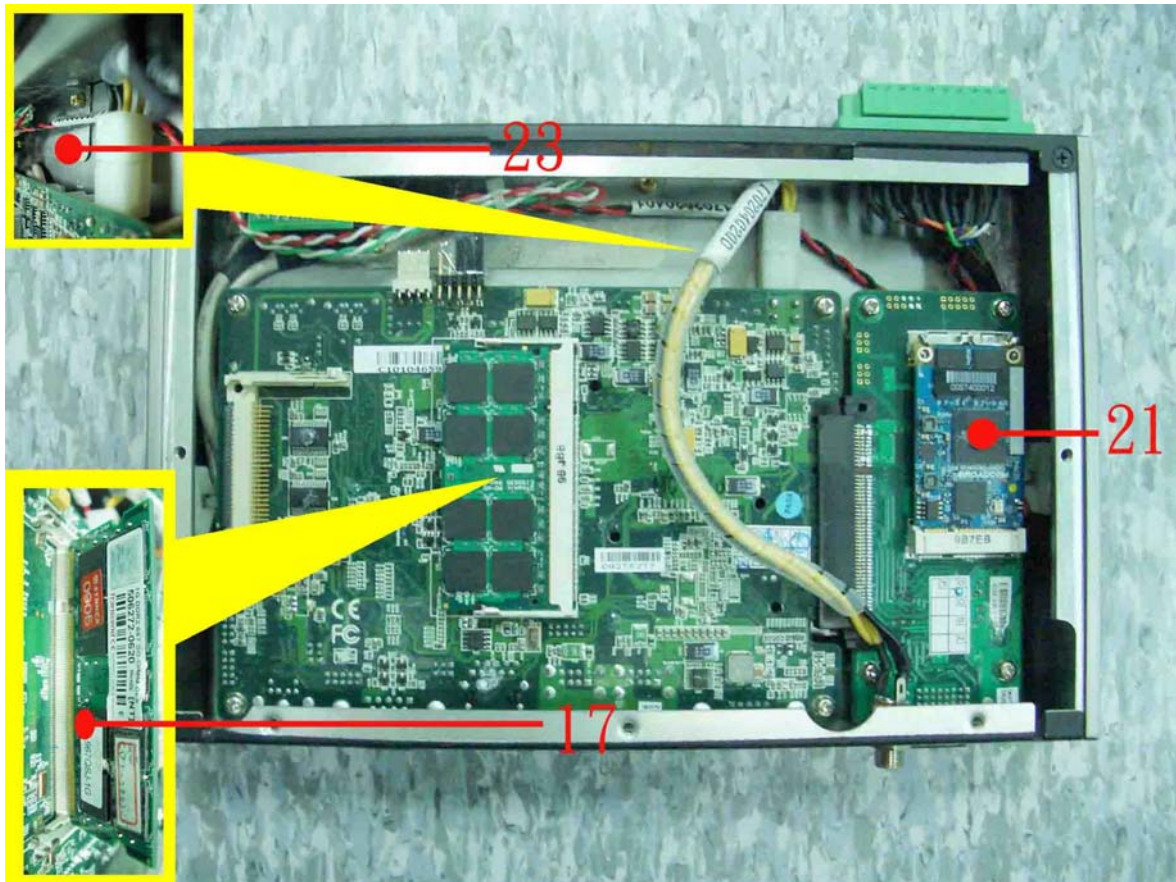
Continuous running till thermal stability (within less than 1°C)

**Test Software:**

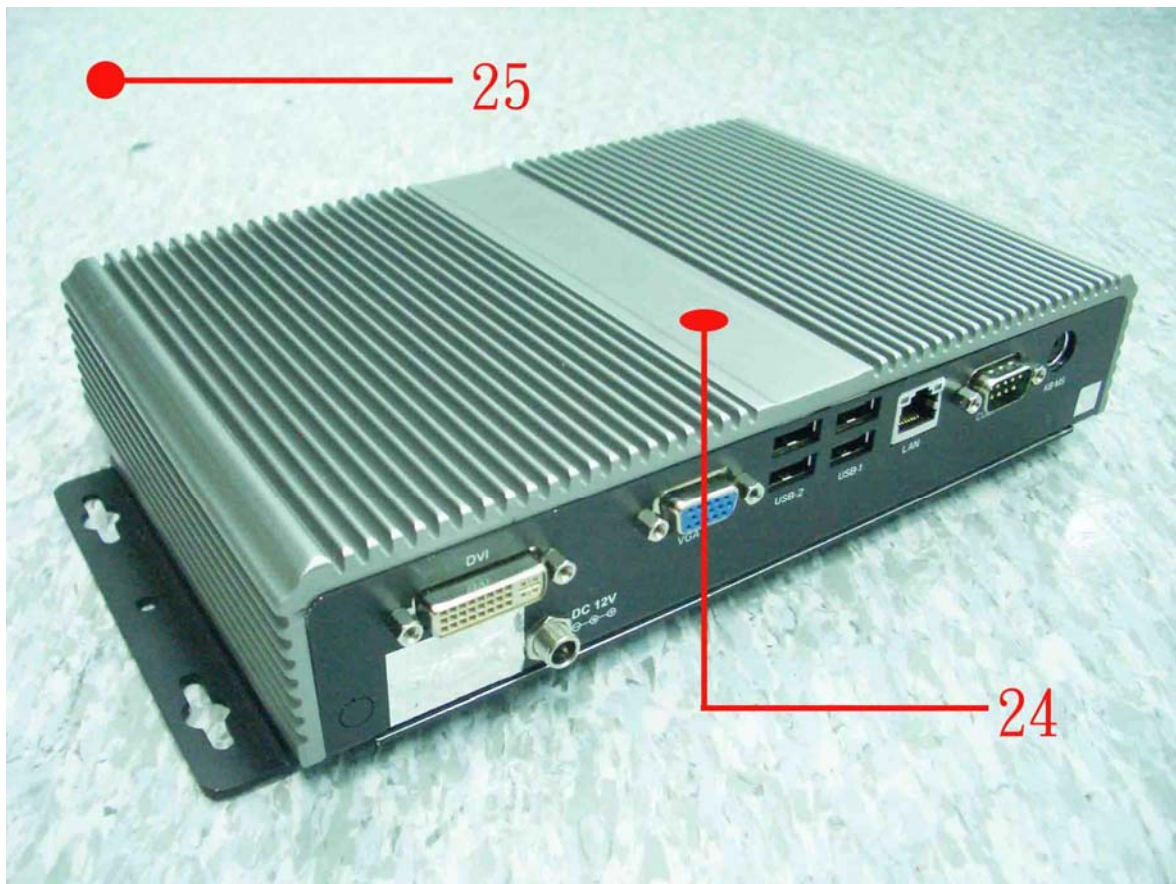
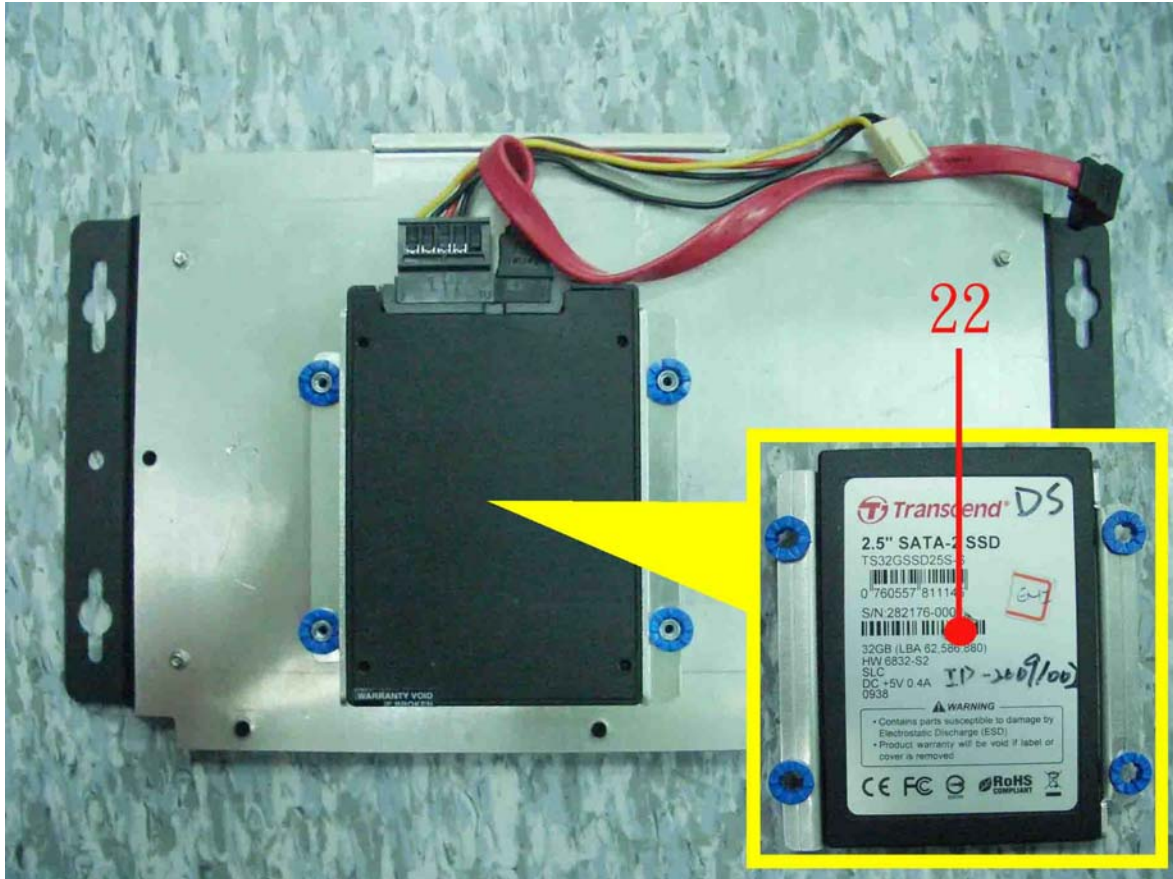
Windows XP / Run PassMark Burn In Test 4.0 Pro

**Terminal Recorder:**

Measuring Thermal Couple Position :



# Temperature rise test



# Temperature rise test

## Thermal profile data:

### FES-6110

Point	Temp. Stage(°C)	Spec	45	25
<b>IMBE-945G</b>				
01. CPU		90	69.0	49.0
02. U10 - (TF) Intel.QG82945GME		105	67.4	47.4
03. U9 - (TF) Chipset ICH7M.Intel.NH82801GBM SL8YB		99	68.7	48.7
04. U13 - (TF) CLOCK GENERATOR.ICS.ICS9LPR501HGLFT		100	85.0	65.0
05. U38 - (TF) Super I/O w/4 COMs.ITE.IT8781F/AX-L		100	75.3	55.3
06. U15 - (TF) 7.1Channel HD Audio Codec.VIA.VT1708B		85	73.2	53.2
07. U19 - (TF) PCI-express.Gigabit Ethernet Chip.REALTEK.RTL8111C-VB-GR		100	78.0	58.0
08. U26 - (TF) IMVP6 Single Phase PWM.Intersil.ISL6261CRZ-T		100	71.0	51.0
09. L5 - (TF) COIL.GOTREND.GSTC063P-3R3MN		125	65.7	45.7
10. L3 - (TF) COIL.GOTREND.GSTC063P-3R3MN		125	84.7	64.7
11. L4 - (TF) BEAD.BLM21PG300SN1D		125	85.4	65.4
12. U1 - (TF) Power Controller.for Dual Channel DDR.INTERASIL.ISL6537ACRZ		100	83.1	63.1
13. L1 - (TF) BEAD.BLM21PG300SN1D		125	78.4	58.4
14. L2 - (TF) BEAD.BLM21PG300SN1D		125	80.3	60.3
15. U39 - (TF) RS232 Driver ESD 15KV.AD.ADM213EARSZ		85	72.0	52.0
16. U40 - (TF) RS232 Driver ESD 15KV.AD.ADM213EARSZ		85	70.7	50.7
17. Memory		85	81.4	61.4
18. Q25 - (TF) PWR.N-Channel POWER MOSFET.FAIRCHILD.FDS6680AS_NL		125	83.4	63.4
19. Q27 - (TF) PWR.N-Channel MOSFET.FAIRCHILD.FDS8896		125	81.6	61.6
20. Q28 - (TF) PWR.N-Channel MOSFET.FAIRCHILD.FDS8896		125	83.8	63.8
<b>AzureWave AW-VD904 Mini Card</b>				
21. U3		85	74.4	54.4
22. SSD		70	66.0	46.0
23. Control Box Inside Air Temperature		N/A	69.1	49.1
24. Control Box External Surface		N/A	64.5	44.5
25. Chamber Air Temperature		N/A	45.0	25.0
<b>Any Tm value showed in red words which meaning the value over the Tc degree C of this device specification.</b>				

# Temperature rise test

## Temperature Measurement Table:

Location	T <sub>A</sub> =45.0°C	Temp. Rise (Thermal Couple)	SpeedFan 4.31 (Read from BIOS)
CPU		69.0°C	79.0°C
System Temp. 1 (North Bridge)		67.4°C	78.0°C
System Temp. 2		N/A	71.0°C

## Sample Configuration & Quantity Under Test:

Quantity: 1 (FES-6110)

## Test Result:

No problem was found during the temperature rise operation test.

# Temperature cycle test

**Test Date:** 03-05~08-2010

**Test Product:** FES-6110

**Test Site:** AAEON QA Internal Lab.

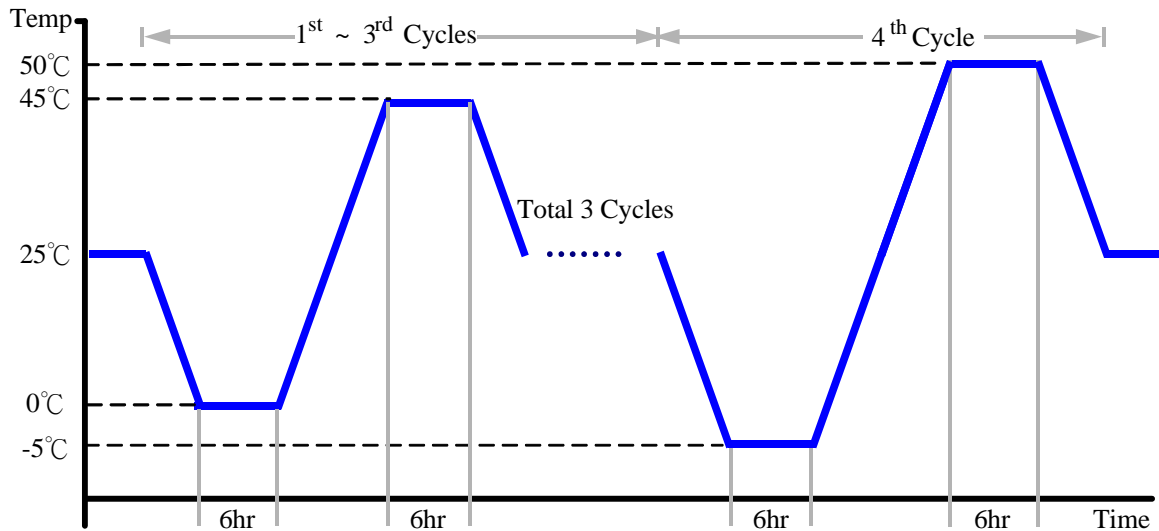
**Test Standard:** Reference IEC68-2-14 Testing procedures  
Test N: Change of temperature Test

**Test Equipment:**

Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-B6T-150+LN2  
Date of Calibration: 04/10/09  
Serial Number: 6488KT

**Test Condition:**

1. Test Low Temperature: 0°C (1~3 cycles)  
-5°C (4<sup>th</sup> cycle)
2. Test High Temperature: 45°C (1~3 cycles)  
50°C (4<sup>th</sup> cycle)
3. Test dwell time: 6Hrs
4. Temperature slope: 2°C/min
5. Test cycle: 4 cycles
6. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (FES-6110)

**Test Result:**

No problem was found during the temperature operation cycle test.



**Test Date:** 03-08~10-2010

**Test Product:** FES-6110

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-2 Testing procedures  
Test Bb: Dry Heat Test (Non-operation)

**Test Equipment:**

Programmable Temperature & Humidity Chamber

K.SON. INS. TECH. CORP.

Model: THS-B6T-150+LN2

Date of Calibration: 04/10/09

Serial Number: 6488KT

**Testing Item:**

1. Test Temperature: 60°C
2. Test Times: 48Hrs
3. Test Software: Windows XP / Run PassMark Burn In Test 4.0 Pro
4. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (FES-6110)

**Test Result:**

No problem was found after the high temperature storage test.

**Test Date:** 03-10~12-2010

**Test Product:** FES-6110

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-1 Testing procedures  
Test Ab: Cold Test (Non-operation)

**Test Equipment:**

Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.

Model: THS-B6T-150+LN2

Date of Calibration: 04/10/09

Serial Number: 6488KT

**Testing Item:**

1. Test Temperature: -20°C
2. Test Times: 48Hrs
3. Test Software: Windows XP / Run PassMark Burn In Test 4.0 Pro
4. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (FES-6110)

**Test Result:**

No problem was found after the low temperature storage test.

**Test Date:** 03-12~15-2010

**Test Product:** FES-6110

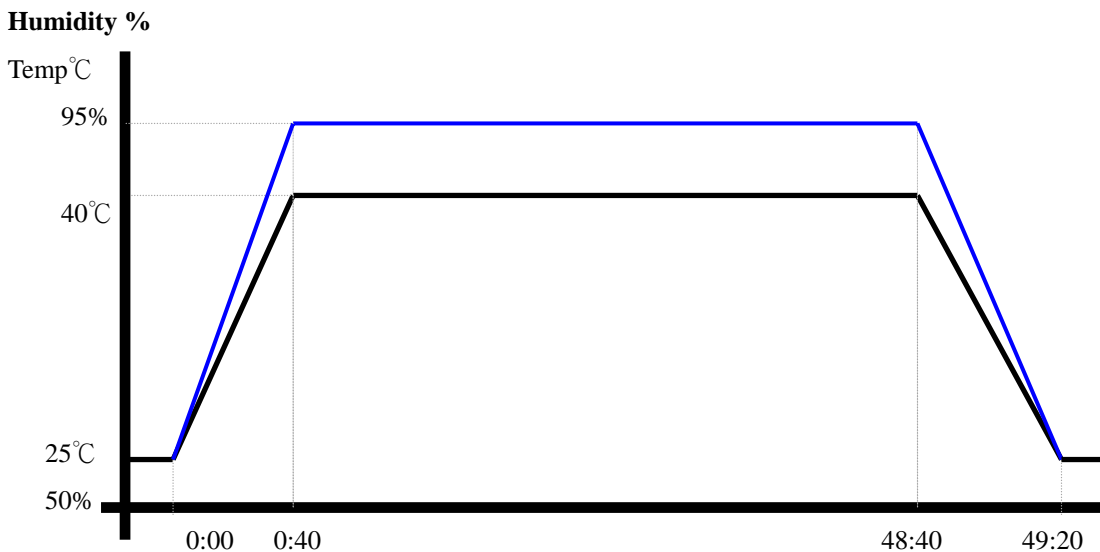
**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-3 Testing procedures  
Test Ca: Damp heat, steady state (Non-operation)

**Test Equipment:**  
Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-B6T-150+LN2  
Date of Calibration: 04/10/09  
Serial Number: 6488KT

**Testing Item:**

1. Test Temperature: 40°C
2. Test Humidity: 95%RH
3. Test Times: 48Hrs
4. Test Software: Windows XP / Run PassMark Burn In Test 4.0 Pro
5. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**  
Quantity: 1 (FES-6110)

**Test Result:**  
No problem was found after the humidity storage test.

# Cold start and hot start test

**Test Date:** 03-16~17-2010

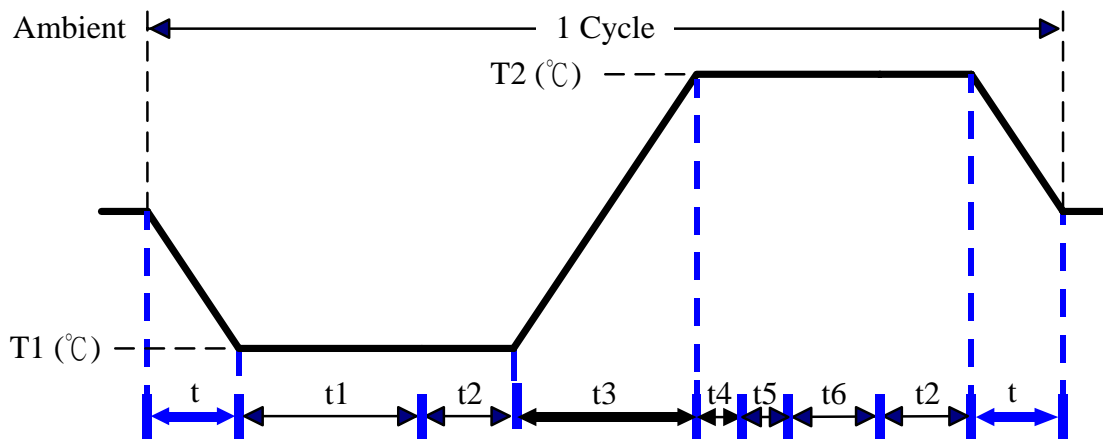
**Test Product:** FES-6110

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-14 Testing procedures  
Test N: Change of temperature Test

**Test Equipment:**  
Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-B6T-150+LN2  
Date of Calibration: 04/10/09  
Serial Number: 6488KT

**Test Condition:**



Parameters	Description
T1	-5°C
T2	50°C
t1	4 hrs
t2, t6	2 hrs
t4, t5	1hrs
t, t3	2°C/min
n (Cycle)	1

t = temprature slope  
t , t1, t6: Power Off  
t2: Power on/off test 10 times (on 2 min / off 5min)  
t3, t4: Run PassMark Burn In Test  
t5: Win XP Software restart test 3 times  
Test Software: Windows XP

**Test Result:**

- a. No problem was found during the cold start test.
- b. No problem was found during the hot start test.